

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 05/18/2022

**Details for "MAX3243CPWRG4"**

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
MAX3243CPWRG4	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	PW   28	4.40x9.70x1.15	176.1

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.16708	99.989228	999892	0.094886	949
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000598	6	0.000001	0
Not Categorized	Proprietary Materials		0.000013	0.00778	78	0.000007	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000001	0.000598	6	0.000001	0
Precious Metals	Silver	7440-22-4	0.000003	0.001795	18	0.000002	0
Sub-Total			0.167098	100	1000000	0.094896	949
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	1.128293	80.000014	800000	0.640767	6408
Thermoplastics	Epoxy	85954-11-6	0.282073	19.999986	200000	0.160191	1602
Sub-Total			1.410366	100	1000000	0.800958	8010
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	96.5448	97.461523	974615	54.828559	548286
Copper and Its Alloys	Iron	7439-89-6	2.277	2.298621	22986	1.293126	12931
Copper and Its Alloys	Phosphorus	7723-14-0	0.0297	0.029982	300	0.016867	169
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.0297	0.029982	300	0.016867	169
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.0297	0.029982	300	0.016867	169
Zinc and Its Alloys	Zinc	7440-66-6	0.1485	0.14991	1499	0.084334	843
Sub-Total			99.0594	100	1000000	56.256621	562566
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	3.8048	95.12	951200	2.160776	21608
Precious Metals	Gold	7440-57-5	0.0312	0.78	7800	0.017719	177
Precious Metals	Palladium	7440-05-3	0.164	4.1	41000	0.093137	931
Sub-Total			4	100	1000000	2.271632	22716
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	57.475592	86.000001	860000	32.640846	326408
Other Plastics and Rubber	Carbon Black	1333-86-4	0.200496	0.3	3000	0.113863	1139
Thermoplastics	Epoxy	85954-11-6	9.155995	13.699999	137000	5.199762	51998
Sub-Total			66.832083	100	1000000	37.954471	379545
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	4.615928	100	1000000	2.621422	26214
Sub-Total			4.615928	100	1000000	2.621422	26214
<b>Total</b>			176.084875			100	1000000

**Important Note**  
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

**Important Part Information**

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.